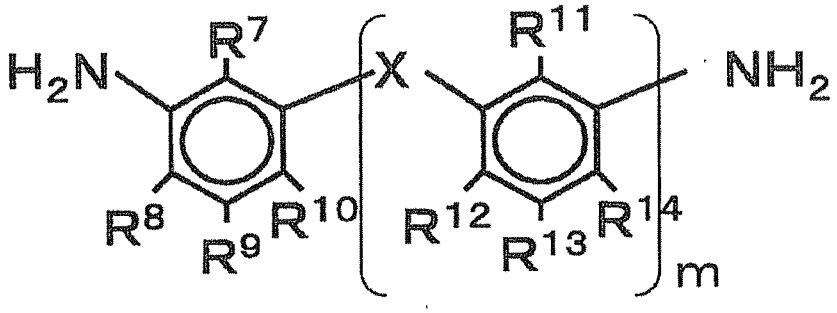
di-amine residue in an amount of 2 to 30 mol% of all di-amine residues.

3. The polyimide resin according to claim 2, wherein the aromatic di-amine is an aromatic di-amine represented by general formula (2),

[Chemical Formula 2]



(2)

wherein m represents an integer within the range of from 1 to 3; X represents a group selected from O, SO_2, CO, CH_2, $C(CH_3)_2$, and $C(CF_3)_2$; R^7 to R^{14} may be the same or different and each represent a group selected from a hydrogen atom, an alkyl group having 1 to 30 carbon atoms, an alkoxy group having 1 to 30 carbon atoms, a hydroxyl group, halogen, a carboxyl group, a sulfone group, a nitro group, and a cyano group.

4. The polyimide resin according to claim 3, wherein the aromatic di-amine represented by general formula (2) is 1,3-bis(3-aminophenoxy)benzene or 3,3'-diamino diphenyl sulfone.

5. The polyimide resin according to claim 4, wherein the aromatic di-amine is 3,3'-diamono diphenyl sulfone.

6. The polyimide resin according to any one of claims 1 to 5, wherein the tetracarboxylic dianhydride residue is a residue of an aromatic tetracarboxylic dianhydride.

7. The polyimide resin according to any one of claims 1 to 6, wherein the polyimide resin is a pressure bonding adhesive.

8. A resin composition comprising at least the polyimide resin according to any one of claims 1 to 7.

9. The resin composition according to claim 8, wherein the glass transition temperature is 30°C or lower.

10. A laminated film in which the resin composition according to claim 8 or 9 is laminated on at least one side of a heat-resistant insulation film.

11. The laminated film according to claim 10, wherein the surface of the heat-resistant insulation film on which the resin composition is laminated is release treated.

12. A laminated film according to claim 10 or 11, wherein a release treated film is further laminated on the surface of the laminated resin composition.